



SOD523 Diodes

Material Content Declaration					
Material name	Substance name e.g. Copper (Cu), Gold (Au)	CAS no., if known	Substance mass (mg)	% OF Weight (%)	ppm Of Total Weight
Lead Frame 59.06%	Nickel (Ni)	7440-02-0	0.587	40.63	345,294.1
	Manganese(Mn)	7439-96-5	0.408	0.82	240,000.0
	Iron(Fe)	7439-89-6	0.001	58.43	588.2
	Silver(Ag)	7440-22-4	0.008	0.12	4,705.9
	Total		1.004		
Bonding Wire 0.11%	Copper (Cu)	7440-50-8	0.002	100.00	1,176.5
	Total		0.002		
Chip 1.83%	Silicon (si)	7440-21-3	0.030	95.40	17,396.5
	Lead (Pb)	7439-92-1	0.001	4.60	838.82
	Total		0.0310		
Molding 38.15%	Silicon powder	7631-86-9	0.4936	76.00	290,352.9
	Epoxy resin	24969-06-0	0.0648	10.00	38,117.6
	Phenolic resin	29690-82-2	0.0518	8.00	30,470.6
	Zinc borate	1332-07-6	0.0324	5.00	19,058.8
	Carbon Black	1333-86-4	0.0064	1.00	3,764.7
	Total		0.649		
Plating 0.85%	Tin (Sn)	7440-31-5	0.014	100.00	8,235.3
	Total		0.014		
	Total mass (mg)				1.700